



SMD Comm X8G HT150C Flex, Ceramic, 11 pF, 1%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



General Information			
Series	SMD Comm X8G HT150C Flex		
Style	SMD Chip		
Description	SMD, MLCC, High Temperature, Ultra-Stable		
Features	High Temperature, Ultra-Stable		
RoHS	Yes		
Termination	Flexible Termination		
Marking	No		
AEC-Q200	No		
Typical Component Weight	30 mg		
Shelf Life	78 Weeks		
MSL	1		

Dimensions		
Chip Size	1210	
L	3.3mm +/-0.4mm	
W	2.6mm +/-0.3mm	
Т	0.78mm +/-0.20mm	
S	1.5mm MIN	
В	0.6mm +/-0.25mm	
В	0.6mm +/-0.25mm	

VV	2.011111 +/ -0.311111			
Т	0.78mm +/-0.20mm			
S	1.5mm MIN			
В	0.6mm +/-0.25mm			
Packaging Specifications				

10000

Packaging

Packaging Quantity

T&R, 330mm, Plastic Tape

Specifications			
Capacitance	11 pF		
Measurement Condition	1 MHz 1.0Vrms		
Tolerance	1%		
Voltage DC	250 VDC		
Dielectric Withstanding Voltage	625 VDC		
Temperature Range	-55/+150°C		
Temp. Coefficient	X8G		
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms		
Dissipation Factor	0.1% 1 MHz 1.0Vrms		
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours		
Insulation Resistance	100 GOhms		

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